Final Product Change Notification

201209019F04

Issue Date: 28-Apr-2013
Effective Date: 28-Jul-2013

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Management Summary

Transfer of TJA1050 High Speed CAN Transceiver to wafer fab ICN8.

Change Category

[X] Wafer Fab process   [X] Assembly Process   [X] Product Marking   [ ] Design
[X] Wafer Fab materials   [X] Assembly Materials   [ ] Electrical spec./Test coverage [ ] Mechanical Specification
[X] Wafer Fab location   [ ] Assembly Location   [ ] Test Location   [ ] Packing/Shipping/Labeling

Transfer of TJA1050 High Speed CAN Transceiver to wafer fab ICN8.

Details of this Change

The A-BCD1 TJA1050 High Speed CAN Transceiver is transferred from the 6" DHAM waferfab in Hamburg, Germany to the 8" ICN8 waferfab in Nijmegen, the Netherlands. This transferred product has also gotten an update to the Bill-Of-Materials (BOM).

Note that, as announced in the Advanced PCN 201209019A, the TJA1050 bare die is not transferred and will be discontinued.

In the attachments to this Final PCN details of the changes involved are given, as well as the AEC-Q100 qualification results for them.

Why do we Implement this Change

The automotive market shows a strong demand for our newest generation Automotive ICs, which are all manufactured in 8" wafer fabs. However, the demand for our mature Automotive ICs remains stronger than expected, which challenges a future in the current 6" production at DHAM for these products. To ensure continued availability for our customers NXP has decided to transfer the main products from DHAM to ICN8.

Please note that there are alternate options available to customer, e.g. upgrade to 3rd generation CAN Transceivers.

Identification of Affected Products

In the attachment to this Final PCN it is shown how the product name and top side marking changes.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 19-Jul-2013

Impact

There is no impact to the product's functionality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 28-May-2013.

Remarks

Please use the links 'view online' above under the heading 'Additional information', to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached documents with relevant detailed information from the tab 'Files'. 'Self qualification' leads to the reliability report, and 'Additional documents' to an attachment with more detailed information on the changes.

Should you not be able to obtain these documents, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

In the NXP e-PCN system on the tab 'Products' you can see a list of your affected part numbers. If you wish to receive the transferred product, you have to order the new NXP 12NC part numbers as mentioned.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Kees van Hasselt
Position	Quality Account Manager
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highest possible Quality Standards.
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NXP Quality Management Team.

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A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of $4.36 billion in 2012.

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